

Data Sheet

Description

The SJPB-D9 is a 90 V, 1.0 A Schottky diode with allowing improvements in V_F and I_R characteristics.

These characteristic features contribute to improving power supply efficiency and to enabling high-frequency systems.

Features

| • | V _{RSM} 90 \ |
|---|---|
| | I _{F(AV)} |
| | $V_F (I_F = 1.0 \text{ A})$ 0.74 V typ |
| | David Land France Dir franc (Dalle Committee) |

- Bare Lead Frame: Pb-free (RoHS Compliant)
- Flammability: Equivalent to UL94V-0
- Suitable for High Reliability and Automotive Requirement

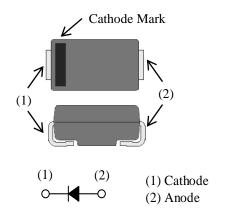
Applications

High speed switching applications as follows:

- DC-DC Converter
- Adapter

Package

SJP



Not to scale

Absolute Maximum Ratings

Unless otherwise specified, $T_A = 25$ °C.

| Parameter | Symbol | Conditions | Rating | Unit |
|------------------------------------|------------------|--|------------|--------|
| Nonrepetitive Peak Reverse Voltage | V_{RSM} | | 90 | V |
| Repetitive Peak Reverse Voltage | V_{RM} | | 90 | V |
| Average Forward Current | $I_{F(AV)}$ | See Figure 2 and Figure 3 | 1.0 | Α |
| Surge Forward Current | I _{FSM} | Half cycle sine wave, positive side, 10 ms, 1 shot | 20 | A |
| I ² t Limiting Value | I^2t | $1 \text{ ms} \le t \le 10 \text{ms}$ | 2.0 | A^2s |
| Junction Temperature | T_{J} | | -40 to 150 | °C |
| Storage Temperature | T_{STG} | | -40 to 150 | °C |

Electrical Characteristics

Unless otherwise specified, $T_A = 25$ °C.

| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
|---|----------------------|---|------|------|------|------|
| Forward Voltage Drop | V_{F} | $I_F = 1.0 A$ | | 0.74 | 0.85 | V |
| Reverse Leakage Current | I_R | $V_R = V_{RM}$ | | _ | 100 | μΑ |
| Reverse Leakage Current under High Temperature | $H \cdot I_R$ | $V_R = V_{RM}$, $T_J = 150 ^{\circ}C$ | | | 30 | mA |
| Thermal Resistance ⁽¹⁾ | $R_{\text{th(J-L)}}$ | | | _ | 20 | °C/W |

Mechanical Characteristics

| Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------------|------------|------|-------|------|------|
| Package Weight | | _ | 0.072 | _ | g |

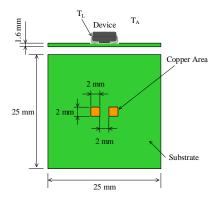


Figure 1. Lead Temperature Measurement Conditions

 $^{^{(1)}}R_{th\,(J-L)}$ is thermal resistance between junction and lead. Lead temperature (T_L) is measured near the root of pin (see Figure 1).

Derating Curves

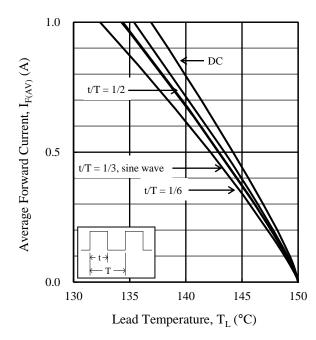


Figure 2. $I_{F(AV)}$ vs. $T_L(T_J = 150 \text{ °C}, V_R = 0 \text{ V})$

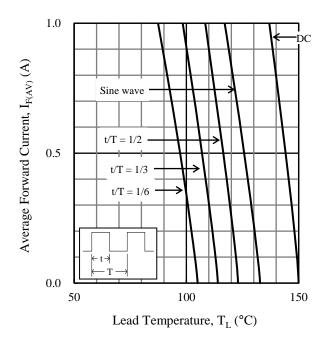


Figure 3. $I_{F(AV)}$ vs. T_L ($T_J = 150$ °C, $V_R = 90$ V)

Characteristic Curves

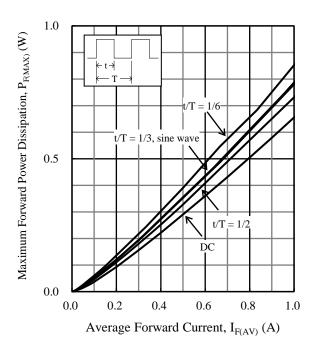


Figure 4. $P_{F(MAX)}$ vs. $I_{F(AV)}$ ($T_J = 150$ °C)

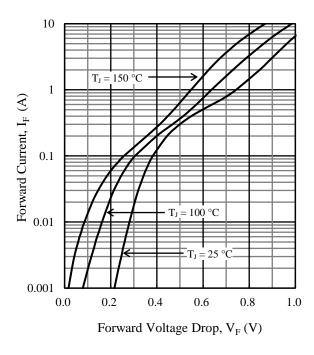


Figure 6. Typical Characteristics: I_F vs. V_F

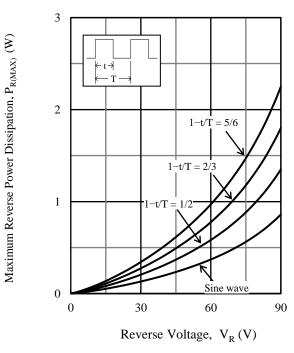


Figure 5. $P_{R(MAX)}$ vs. V_R ($T_J = 150$ °C)

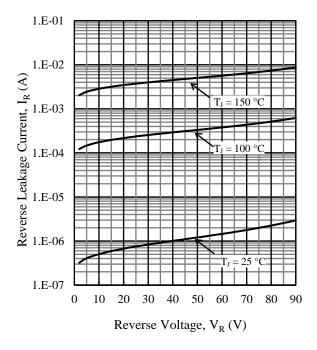


Figure 7. Typical Characteristics: I_R vs. V_R

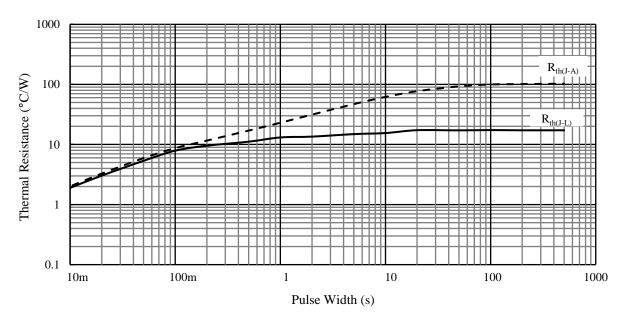
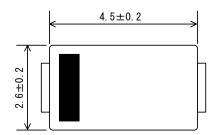
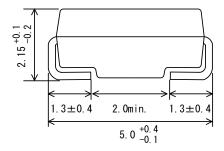


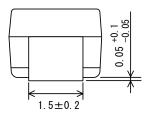
Figure 8. Typical Transient Thermal Resistance Characteristics

Physical Dimensions

• SJP Package







NOTES:

- Dimensions in millimeters
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits:
- Flow: 260 °C / 10 s, 1 time

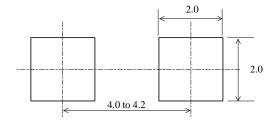
Reflow:

Preheat: 150 °C to 200 °C / 60 s to 120 s

Solder heating: 255 °C / 30s, 3 times (260 °C peak)

Soldering Iron: 350 °C / 3.5 s, 1 time

• SJP Land Pattern Example



NOTE:

- Dimensions in millimeters

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Marking Diagram

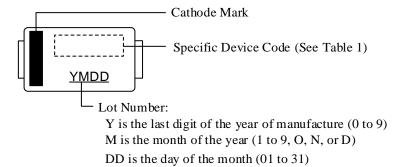


Table 1. Specific Device Code

| Specific Device Code | Part Number |
|----------------------|-------------|
| BD9 | SJPB-D9 |

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